

PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT | | | | | | | | | | | | | | | | | | | | | | |
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| CONVEYING PARTY DATA | | | | | | | | | | | | | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>MAKOTO YOSHIKAWA</td> <td>07/17/2013</td> </tr> <tr> <td>HIRONORI IIDA</td> <td>07/08/2013</td> </tr> <tr> <td>TAKASHI OBIKAWA</td> <td>07/20/2013</td> </tr> <tr> <td>SHINICHIRO YAMADA</td> <td>07/08/2013</td> </tr> <tr> <td>SEIICHIRO TABATA</td> <td>07/08/2013</td> </tr> <tr> <td>KAZUMA USAMI</td> <td>07/05/2013</td> </tr> <tr> <td>MASAKAZU MITSUGI</td> <td>07/09/2013</td> </tr> <tr> <td>HIROTSUGU ISHIHARA</td> <td>07/25/2013</td> </tr> <tr> <td>SHUN YAMANOI</td> <td>07/18/2013</td> </tr> <tr> <td>MACHIKO MINATOYA</td> <td>07/06/2013</td> </tr> </tbody> </table> | | Name | Execution Date | MAKOTO YOSHIKAWA | 07/17/2013 | HIRONORI IIDA | 07/08/2013 | TAKASHI OBIKAWA | 07/20/2013 | SHINICHIRO YAMADA | 07/08/2013 | SEIICHIRO TABATA | 07/08/2013 | KAZUMA USAMI | 07/05/2013 | MASAKAZU MITSUGI | 07/09/2013 | HIROTSUGU ISHIHARA | 07/25/2013 | SHUN YAMANOI | 07/18/2013 | MACHIKO MINATOYA | 07/06/2013 |
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| MAKOTO YOSHIKAWA | 07/17/2013 | | | | | | | | | | | | | | | | | | | | | | |
| HIRONORI IIDA | 07/08/2013 | | | | | | | | | | | | | | | | | | | | | | |
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| SHINICHIRO YAMADA | 07/08/2013 | | | | | | | | | | | | | | | | | | | | | | |
| SEIICHIRO TABATA | 07/08/2013 | | | | | | | | | | | | | | | | | | | | | | |
| KAZUMA USAMI | 07/05/2013 | | | | | | | | | | | | | | | | | | | | | | |
| MASAKAZU MITSUGI | 07/09/2013 | | | | | | | | | | | | | | | | | | | | | | |
| HIROTSUGU ISHIHARA | 07/25/2013 | | | | | | | | | | | | | | | | | | | | | | |
| SHUN YAMANOI | 07/18/2013 | | | | | | | | | | | | | | | | | | | | | | |
| MACHIKO MINATOYA | 07/06/2013 | | | | | | | | | | | | | | | | | | | | | | |
| RECEIVING PARTY DATA | | | | | | | | | | | | | | | | | | | | | | | |
| Name: | SONY CORPORATION | | | | | | | | | | | | | | | | | | | | | | |
| Street Address: | 1-7-1 KONAN, MINATO-KU | | | | | | | | | | | | | | | | | | | | | | |
| City: | TOKYO | | | | | | | | | | | | | | | | | | | | | | |
| State/Country: | JAPAN | | | | | | | | | | | | | | | | | | | | | | |
| Postal Code: | 108-0075 | | | | | | | | | | | | | | | | | | | | | | |
| PROPERTY NUMBERS Total: 1 | | | | | | | | | | | | | | | | | | | | | | | |
| <table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14006187</td> </tr> </tbody> </table> | | Property Type | Number | Application Number: | 14006187 | | | | | | | | | | | | | | | | | | |
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| Application Number: | 14006187 | | | | | | | | | | | | | | | | | | | | | | |
| CORRESPONDENCE DATA | | | | | | | | | | | | | | | | | | | | | | | |
| Fax Number: | (617)646-8646 | | | | | | | | | | | | | | | | | | | | | | |
| Phone: | 6176468000 | | | | | | | | | | | | | | | | | | | | | | |
| Email: | patents_SonyAdmins@wolfgreenfield.com, vbowden@wolfgreenfield.com | | | | | | | | | | | | | | | | | | | | | | |
| <i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i> | | | | | | | | | | | | | | | | | | | | | | | |
| Correspondent Name: | WOLF GREENFIELD & SACKS, P.C. | | | | | | | | | | | | | | | | | | | | | | |
| Address Line 1: | 600 ATLANTIC AVENUE | | | | | | | | | | | | | | | | | | | | | | |

OP \$40.00 14006187

Address Line 2: RANDY J. PRITZKER, ESQ.
Address Line 4: BOSTON, MASSACHUSETTS 02210

ATTORNEY DOCKET NUMBER: S1459.71202US00

NAME OF SUBMITTER: VALERIE J. BOWDEN

Signature: /Valerie J. Bowden/

Date: 12/05/2013

Total Attachments: 12

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ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
POROUS CARBON MATERIAL, ADSORBENT, ORAL ADSORBENT, MEDICAL ADSORBENT, FILLER FOR BLOOD PURIFICATION COLUMN, WATER PURIFICATION ADSORBENT, CLEANSING AGENT, CARRIER, SUSTAINED RELEASE PHARMACEUTICAL, CELL CULTURE SCAFFOLD, MASK, CARBON/POLYMER COMPOSITE, ADSORBENT SHEET AND FUNCTIONAL FOOD
for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Application No.: PCT/JP2012/001565, International Filing Date: 2012/03/07

This assignment executed on the dates indicated below.

MAKOTO YOSHIZAKI

Name of first or sole inventor

KANAGAWA, JAPAN

Residence of First or sole inventor

Makoto Yoshizaki

Signature of first or sole inventor

Execution date of U.S. Patent Application

July 17, 2013

Date of this assignment

HIRONORI IIDA

Name of second inventor

KANAGAWA, JAPAN

Residence of second inventor

Signature of second inventor

Execution date of U.S. Patent Application

Date of this assignment

TAKASHI OBIKAWA

Name of third inventor

KANAGAWA, JAPAN

Residence of third inventor

Signature of third inventor

Execution date of U.S. Patent Application

Date of this assignment

ADDITIONAL INVENTOR(S)

SHINICHIRO YAMADA

Name of fourth inventor

KANAGAWA, JAPAN

Residence of fourth inventor

Signature of fourth inventor

Execution date of U.S. Patent Application

Date of this assignment

SEIICHIRO TABATA

Name of fifth inventor

KANAGAWA, JAPAN

Residence of fifth inventor

Signature of fifth inventor

Execution date of U.S. Patent Application

Date of this assignment

KAZUMA USAMI

Name of sixth inventor

KANAGAWA, JAPAN

Residence of sixth inventor

Signature of sixth inventor

Execution date of U.S. Patent Application

Date of this assignment

MASAKAZU MITSUGI

Name of seventh inventor

KANAGAWA, JAPAN

Residence of seventh inventor

Signature of seventh inventor

Execution date of U.S. Patent Application

Date of this assignment

HIROTSUGU ISHIHARA

Name of eighth inventor

TOKYO, JAPAN

Residence of eighth inventor

Signature of eighth inventor

Execution date of U.S. Patent Application

Date of this assignment

SHUN YAMANOI

Name of ninth inventor

KANAGAWA, JAPAN

Residence of ninth inventor

Signature of ninth inventor

Execution date of U.S. Patent Application

Date of this assignment

ADDITIONAL INVENTOR(S)

MACHIKO MINATOYA

Name of tenth inventor

TOKYO, JAPAN

Residence of tenth inventor

Execution date of U.S. Patent Application

Signature of tenth inventor

Date of this assignment

Name of eleventh inventor

Execution date of U.S. Patent Application

Residence of eleventh inventor

Signature of eleventh inventor

Date of this assignment

Name of twelfth inventor

Execution date of U.S. Patent Application

Residence of twelfth inventor

Signature of twelfth inventor

Date of this assignment

Name of thirteen inventor

Execution date of U.S. Patent Application

Residence of thirteen inventor

Signature of thirteen inventor

Date of this assignment

Name of fourteen inventor

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Signature of fourteen inventor

Date of this assignment

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Signature of fifteen inventor

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Name of first or sole inventor

KANAGAWA, JAPAN

Residence of First or sole inventor

Signature of first or sole inventor

Execution date of U.S. Patent Application

Date of this assignment

HIRONORI IIDA

Name of second inventor

KANAGAWA, JAPAN

Residence of second inventor

Hironori Iida
Signature of second inventor

Execution date of U.S. Patent Application

July 8, 2013
Date of this assignment

TAKASHI OBIKAWA

Name of third inventor

KANAGAWA, JAPAN

Residence of third inventor

Takashi Obikawa
Signature of third inventor

Execution date of U.S. Patent Application

July 20, 2013
Date of this assignment

ADDITIONAL INVENTOR(S)

SHINICHIRO YAMADA

Name of fourth inventor

KANAGAWA, JAPAN

Residence of fourth inventor

Shinichi Yamada

Signature of fourth inventor

Execution date of U.S. Patent Application

July 8, 2013

Date of this assignment

SEIICHIRO TABATA

Name of fifth inventor

KANAGAWA, JAPAN

Residence of fifth inventor

Seiichiro Tabata

Signature of fifth inventor

Execution date of U.S. Patent Application

July 8, 2013

Date of this assignment

KAZUMA USAMI

Name of sixth inventor

KANAGAWA, JAPAN

Residence of sixth inventor

Signature of sixth inventor

Execution date of U.S. Patent Application

Date of this assignment

MASAKAZU MITSUGI

Name of seventh inventor

KANAGAWA, JAPAN

Residence of seventh inventor

Signature of seventh inventor

Execution date of U.S. Patent Application

Date of this assignment

HIROTSUGU ISHIHARA

Name of eighth inventor

TOKYO, JAPAN

Residence of eighth inventor

Signature of eighth inventor

Execution date of U.S. Patent Application

Date of this assignment

SHUN YAMANOI

Name of ninth inventor

KANAGAWA, JAPAN

Residence of ninth inventor

Signature of ninth inventor

Execution date of U.S. Patent Application

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ADDITIONAL INVENTOR(S)

MACHIKO MINATOYA

Name of tenth inventor

TOKYO, JAPAN

Residence of tenth inventor

Signature of tenth inventor

Execution date of U.S. Patent Application

Date of this assignment

Name of eleventh inventor

Residence of eleventh inventor

Signature of eleventh inventor

Execution date of U.S. Patent Application

Date of this assignment

Name of twelfth inventor

Residence of twelfth inventor

Signature of twelfth inventor

Execution date of U.S. Patent Application

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Name of thirteen inventor

Residence of thirteen inventor

Signature of thirteen inventor

Execution date of U.S. Patent Application

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KANAGAWA, JAPAN

Residence of First or sole inventor

Signature of first or sole inventor

Execution date of U.S. Patent Application

Date of this assignment

HIRONORI IIDA

Name of second inventor
KANAGAWA, JAPAN

Residence of second inventor

Signature of second inventor

Execution date of U.S. Patent Application

Date of this assignment

TAKASHI OBIKAWA

Name of third inventor
KANAGAWA, JAPAN

Residence of third inventor

Signature of third inventor

Execution date of U.S. Patent Application

Date of this assignment

ADDITIONAL INVENTOR(S)

SHINICHIRO YAMADA

Name of fourth inventor

KANAGAWA, JAPAN

Residence of fourth inventor

Signature of fourth inventor

Execution date of U.S. Patent Application

Date of this assignment

SEIICHIRO TABATA

Name of fifth inventor

KANAGAWA, JAPAN

Residence of fifth inventor

Signature of fifth inventor

Execution date of U.S. Patent Application

Date of this assignment

KAZUMA USAMI

Name of sixth inventor

KANAGAWA, JAPAN

Residence of sixth inventor

Kazuma Usami
Signature of sixth inventor

Execution date of U.S. Patent Application

July 5, 2013
Date of this assignment

MASAKAZU MITSUGI

Name of seventh inventor

KANAGAWA, JAPAN

Residence of seventh inventor

Masakazu Mitsugi
Signature of seventh inventor

Execution date of U.S. Patent Application

July 9, 2013
Date of this assignment

HIROTSUGU ISHIHARA

Name of eighth inventor

TOKYO, JAPAN

Residence of eighth inventor

Hirotsugu Ishihara
Signature of eighth inventor

Execution date of U.S. Patent Application

July 25, 2013
Date of this assignment

SHUN YAMANOI

Name of ninth inventor

KANAGAWA, JAPAN

Residence of ninth inventor

Shun Yamanoi
Signature of ninth inventor

Execution date of U.S. Patent Application

July 18, 2013
Date of this assignment

ADDITIONAL INVENTOR(S)

MACHIKO MINATOYA

Name of tenth inventor

TOKYO, JAPAN

Residence of tenth inventor

Signature of tenth inventor

Execution date of U.S. Patent Application

Date of this assignment

Name of eleventh inventor

Residence of eleventh inventor

Signature of eleventh inventor

Execution date of U.S. Patent Application

Date of this assignment

Name of twelfth inventor

Residence of twelfth inventor

Signature of twelfth inventor

Execution date of U.S. Patent Application

Date of this assignment

Name of thirteen inventor

Residence of thirteen inventor

Signature of thirteen inventor

Execution date of U.S. Patent Application

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Name of fourteen inventor

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And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Application No.: PCT/JP2012/001565, International Filing Date: 2012/03/07

This assignment executed on the dates indicated below.

MAKOTO YOSHIZAKI

Name of first or sole inventor
KANAGAWA, JAPAN

Residence of First or sole inventor

Signature of first or sole inventor

Execution date of U.S. Patent Application

Date of this assignment

HIRONORI IIDA

Name of second inventor
KANAGAWA, JAPAN

Residence of second inventor

Signature of second inventor

Execution date of U.S. Patent Application

Date of this assignment

TAKASHI OBIKAWA

Name of third inventor
KANAGAWA, JAPAN

Residence of third inventor

Signature of third inventor

Execution date of U.S. Patent Application

Date of this assignment

ADDITIONAL INVENTOR(S)

SHINICHIRO YAMADA

Name of fourth inventor

KANAGAWA, JAPAN

Residence of fourth inventor

Execution date of U.S. Patent Application

Signature of fourth inventor

Date of this assignment

SEIICHIRO TABATA

Name of fifth inventor

KANAGAWA, JAPAN

Residence of fifth inventor

Execution date of U.S. Patent Application

Signature of fifth inventor

Date of this assignment

KAZUMA USAMI

Name of sixth inventor

KANAGAWA, JAPAN

Residence of sixth inventor

Execution date of U.S. Patent Application

Signature of sixth inventor

Date of this assignment

MASAKAZU MITSUGI

Name of seventh inventor

KANAGAWA, JAPAN

Residence of seventh inventor

Execution date of U.S. Patent Application

Signature of seventh inventor

Date of this assignment

HIROTSUGU ISHIHARA

Name of eighth inventor

TOKYO, JAPAN

Residence of eighth inventor

Execution date of U.S. Patent Application

Signature of eighth inventor

Date of this assignment

SHUN YAMANOI

Name of ninth inventor

KANAGAWA, JAPAN

Residence of ninth inventor

Execution date of U.S. Patent Application

Signature of ninth inventor

Date of this assignment

